



IFW

542-005.15

UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of :
D. Nakamura et al :
Serial No. 10/722,163 : Examiner: B. Chervinsky
Filed: November 25, 2003 : Group Art Unit: 2835
For: HEAT DISSIPATING STRUCTURE OF PRINTED CIRCUIT BOARD
AND FABRICATING METHOD THEREOF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

ELECTION

Sir:

In response to the Official Action of January 6, 2005,
please amend the above-referenced application as follows:

I hereby certify that this correspondence is
being deposited today with the United States
Postal Service as first class mail in an
envelope addressed to: Commissioner for
Patents, P.O. Box 1450, Alexandria, VA,
22313-1450.

Marilyn O'Connell
Marilyn O'Connell

February 2, 2005
Date